

**Amendments to the Claims:**

This listing of claims will replace all prior versions, and listings, of claims in the application:

**Listing of Claims:**

1. (currently amended) A method of packaging an integrated ~~[[circuits]]~~ circuit, comprising:  
  
disposing an integrated circuit chip outwardly from a first surface of a substrate;  
  
positioning the integrated circuit chip and the substrate between a first mold press die and a second mold press die;  
  
engaging the first mold press die with the second mold press die such that the integrated circuit chip is disposed within a cavity formed by the engagement of the first mold press die with the second mold press die, the cavity comprising a pre-warped configuration based on an anticipated warpage of a mold compound when removed from the cavity and further based on a predefined configuration of the mold compound after curing;  
  
~~determining a pre-warped configuration for the cavity;~~ and  
  
encapsulating the integrated circuit chip with ~~[[a]]~~ the mold compound such that the mold compound takes on the pre-warped configuration of the cavity;  
  
removing the encapsulated integrated circuit chip from the cavity; and  
  
curing the mold compound, whereby the curing transforms the mold compound from the pre-warped configuration to a predefined configuration.
2. (original) The method of Claim 1, further comprising coupling a plurality of solder balls to a second surface of the substrate opposite the first surface.
3. (original) The method of Claim 1, further comprising disposing a leadframe around a periphery of the integrated circuit chip before the encapsulating step.
4. (original) The method of Claim 1, wherein the pre-warped configuration of the cavity is defined by a first non-planar surface on the first mold press die and a second non-planar surface on the second mold press die.

5. (original) The method of Claim 1, wherein the pre-warped configuration of the cavity is defined by a concave surface on the first mold press die and a convex surface on the second mold press die.
6. (original) The method of Claim 1, wherein the predefined configuration substantially resembles a rectangular parallelepiped.
7. (currently amended) The method of Claim 1, wherein the integrated circuit ~~[[packages comprise]]~~ package comprises a ball grid arrays.
8. (currently amended) The method of Claim 1, wherein the integrated circuit ~~[[packages comprise]]~~ package comprises a quad flat packages.

9. (currently amended) A system for packaging an integrated ~~[[circuits]]~~ circuit, comprising:

an integrated circuit chip disposed outwardly from a first surface of a substrate;

a first mold press die comprising a first non-planar surface;

a second mold press die comprising a second non-planar surface;

the first and second non-planar surfaces forming upper and lower surfaces of a cavity when the first and second mold press die are engaged; and

the cavity having a pre-warped configuration based on an anticipated warpage of a mold compound when removed from the cavity and further based on a predefined configuration of the mold compound after curing. ~~and~~

~~a mold compound adapted to fill the cavity and encapsulate the integrated circuit chip, the mold compound adapted to transform from the pre-warped configuration to a predefined configuration after curing of the mold compound.~~

10. (original) The system of Claim 9, further comprising a plurality of solder balls coupled to a second surface of the substrate opposite the first surface.

11. (original) The system of Claim 9, further comprising a leadframe disposed around a periphery of the integrated circuit chip.

12. (original) The system of Claim 9, wherein the first non-planar surface comprises a concave surface and the second non-planar surface comprises a convex surface.

13. (original) The system of Claim 9, wherein the predefined configuration substantially resembles a rectangular parallelepiped.

14. (currently amended) The system of Claim 9, wherein the integrated circuit ~~[[packages comprise]]~~ package comprises a ball grid arrays.

15. (currently amended) The system of Claim 9, wherein the integrated circuit ~~[[packages comprise]]~~ package comprises a quad flat packages.

16. (currently amended) A method of packaging an integrated [[circuits]] circuit, comprising:

providing a substrate;

providing an integrated circuit chip adapted to couple to the substrate;

providing a first mold press die comprising a first non-planar surface;

providing a second mold press die comprising a second non-planar surface, the first and second non-planar surfaces forming upper and lower surfaces of a cavity when the first and second mold press die are engaged;

providing a mold compound adapted to fill the cavity and encapsulate the integrated circuit chip;

determining a pre-warped configuration for the cavity based on an anticipated warpage of the mold compound when removed from the cavity and further based on a predefined configuration of the mold compound after curing; and

causing the cavity to resemble the pre-warped configuration by shaping the first and second non-planar surfaces, whereby the mold compound is adapted to transform from the pre-warped configuration to a predefined configuration during the curing of the mold compound.

17. (original) The method of Claim 16, wherein the first non-planar surface comprises a concave surface and the second non-planar surface comprises a convex surface.

18. (original) The method of Claim 16, wherein the predefined configuration substantially resembles a rectangular parallelepiped.

19. (currently amended) The method of Claim 16, wherein the integrated circuit [[packages comprise]] package comprises a ball grid arrays.

20. (original) The method of Claim 16, wherein the integrated circuit [[packages comprise]] package comprises a quad flat packages.